Intelligent sensor system maximizes battery life: Interfacing the MSP430F123 Flash MCU, ADS7822, and TPS60311

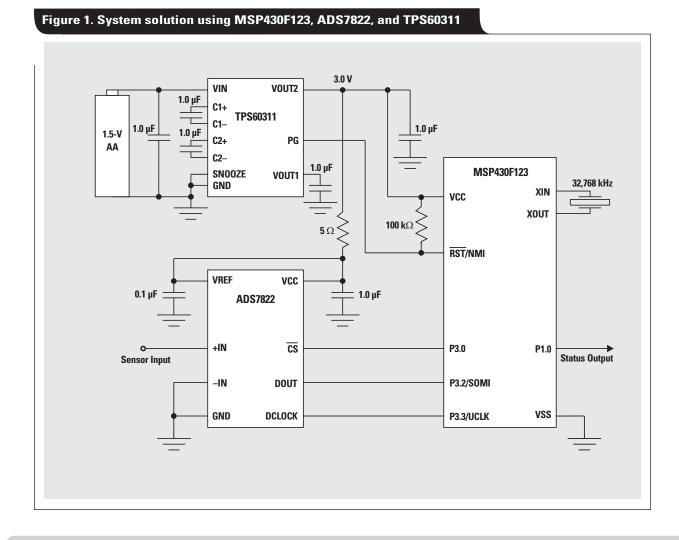
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Introduction

This article describes how to use event-driven techniques to maintain the lowest possible power consumption in single-cell, battery-powered intelligent sensor applications. These applications detect such things as glass breakage, sound level, fire, and smoke. The same applications include a microcontroller unit (MCU) to control the system and a high-resolution, analog-to-digital converter (ADC) to search periodically for interesting real-time sensor output signals. To extend battery life, system power consumption must be managed to the absolute lowest possible level. To reduce power consumption, intuition points to a slowly operating data acquisition solution. On the surface this intuitive approach seems reasonable; but it is misleading, especially when analog circuitry is involved. Although power consumption does typically scale with conversion rate, it will be demonstrated that extending system time in standby modes is the largest contributor to total power reduction. Activity must occur as fast as possible in short "bursts," allowing the system to return quickly to a standby mode. A micropower intelligent sensor system using the MSP430F123 Flash MCU, ADS7822 12-bit ADC, and a single-cell TPS60311 dc/dc boost converter is examined. The entire system is powered from a common 1.5-V AA battery. See Figure 1.

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Enabling single-cell, 3-year battery life

The example examined is powered from a single 1.5-V AA alkaline battery with a typical usable energy value of 1,000 mAh. If the application has a targeted 3-year battery life, total current consumption must be managed as follows:

1,000 mAh/3 years/365 days/24 hours = 38.0 $\mu A.$

The example presented also assumes that the sensor must be sampled at a 2-ms interval (512 samples per second) to acquire the necessary real-time data to detect an event such as glass breakage.

Serial interface

The interface between the MSP430F123 MCU and ADS7822 ADC is glueless. The MCU's integrated USART peripheral is used in SPI master mode to drive communication with the ADC. The USART clock (UCLK) is provided to the ADC (DCLOCK), and receives data on the slave out master (SOMI) from the ADC digital output DOUT. In the example, software uses port pin P3.0 to control the ADC chip select (\overline{CS}). Any available port pin can be used. With $\overline{\text{CS}}$ and software, the MCU directly enables and disables the ADC. The ADS7822 provides 15 bits of data: 2 bits for sampling, 1 null bit, and 12 bits of conversion code. Typically, SPI serial communication exchanges data as 8-bit bytes. To transfer the 15 bits from ADS7822 to the MSP430, two 8-bit transfers are made back-to-back and packed into a single 16-bit word by using software. The word data is rotated right to eliminate the erroneous extra bit and is then AND'ed with 0FFFh to expose only the interesting 12 bits of ADC conversion code. The result is right justified.

The MCU enables the ADC by resetting $\overline{\text{CS}}$. The conversion is started and timed with 16 bits of data exchanged by writing two dummy bytes back-to-back to the USART transmit buffer (TXBUF). TXBUF is double buffered, so back-to-back 8-bit writes will transfer a total of 16 bits. Though no data is actually transmitted from the MCU, writing to TXBUF automatically initiates a complete bidirectional SPI transfer, including UCLK generation that

is required by the ADC DCLOCK. The data transmit function of the USART is simply ignored. After the first 8-bit byte of data is received from the ADC into the USART shift register, it is transferred automatically to the receive buffer (RXBUF). The second byte of data is automatically received next as software is recovering the first byte from RXBUF. The second byte of data is recovered; then the 16-bit result is packed into register R15. See Figure 2.

Slow operating system analysis

First consider the intuitive approach to saving power; that is, simply clock the entire system slow from the available 32-kHz watch crystal. With the MSP430 CPU master clock (MCLK) clocked continuously at 32 kHz, current consumption is approximately 10–12 μ A. With this slow clocking, the MCU will be essentially 100% active in order to complete the required sample and decision loop at the 2-ms interval. No standby modes are possible. The SPI UCLK at 1,6384 Hz (32,768/2) can conveniently clock the ADC DCLOCK. With 16 clocks per sample, the ADC can complete a conversion in approximately 1 ms, leaving 1 ms for power-down and time for the MCU to complete the calculation. The active current of the ADS7822 is approximately 200 μ A. Powered down, the ADC current consumption is a negligible 50 nA. The MCU will be 100% active, and the ADC 50% active.

In snooze mode, quiescent current of the TPS60311 dc/dc charge pump is 2.0 µA typical and can deliver 2 mA to the system. Since the system should never use more than 2 mA, and the 2-µA TPS60311 snooze current will be a constant draw, snooze should be the only mode ever used.

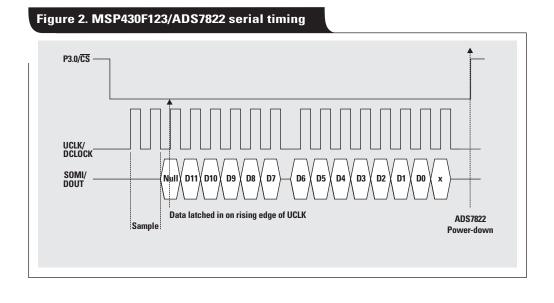
With slow (32-kHz) processing, the system consumes an average current as calculated:

 $I_{BAT} = MCU + ADC + dc/dc$

- = $(10 \ \mu\text{A} \times 1.00) + (200 \ \mu\text{A} \times 0.50) + (2 \ \mu\text{A})$
- = $10 \ \mu A + 100 \ \mu A + 2 \ \mu A$

= 112 µA.

At an average current consumption of 112 μ A, the system exceeds the 38- μ A maximum for 3-year, single-cell battery life. The most significant current consumption is the 50%



active duty cycle for the ADC. The analog circuitry of the ADC is the prime current consumer and is largely unaffected by speed of conversion. The ADC's total current consumption is approximately 200 μ A and is almost unchanged over the full DCLOCK range of operation at 10 kHz–1.2 MHz. With this in mind, it makes sense to convert as fast as possible and spend as much time as possible in power down. With a slow 32-kHz MCLK, the MCU is 100% active; no standby mode is possible and no processing bandwidth available for increased digital signal processing or additional sensor sampling.

Burst mode system analysis

Next consider a burst technique-fast, short active-mode intervals with extended system time in standby. The MSP430 is clocked by a single 32-kHz watch crystal that drives an internal auxiliary clock (ACLK). The ACLK is used in the example to drive only the watchdog timer (WDT), configured by software as a 2-ms-interval timer. As configured, the MCU operates normally in low-power mode 3 (LPM3) with only the ACLK and WDT interrupt active. At the programmed 2-ms interval, the WDT interrupts the system and activates the CPU, which is then driven by a high-speed MCLK clocked from the on-chip digitally controlled oscillator (DCO). It is important to note that the fast-starting DCO also allows the MCU to move from standby to high-speed active mode in less than 6 µs. The DCO has been configured by software to operate in the 1-MHz range. The sub-master clock (SMCLK) used by the USART has also been configured to clock from the DCO.

As defined by the programmed WDT interrupt interval, the ADC is sampled and a decision made every 2 ms.

The ADC measurement and decision code requires approximately 70 active CPU MCLK clocks. At 512 measurements/decisions per second, the CPU is active a total of 70 \times 512 = 35,840 clocks per second. Assuming that the CPU is clocked at 1 MHz (1 µs per clock), the active duty cycle for the CPU is 35,840/1,000,000 = 3.5%. The MCU active current is approximately 300 µA. The standby mode LPM3 current is 1.6 µA and is dominant 96.5% of the application time. Using a 500-kHz DCLOCK (1 MHz/2), the system samples the ADS7822 512 times per second, with each sample taking 16 clocks. The ADC will be 1.6% active and 98.4% powered down.

For maximum power conservation, the MCU manages the system such that MCU and ADC spend the vast majority of time in standby mode, with an average standby current consumption of all components $\sim 3.6 \ \mu$ A.

With a burst-mode technique, the system consumes an average current as calculated:

 $I_{BAT} = MCU + ADC + dc/dc$

=
$$(1.6 \ \mu A \times 0.965 + 300 \ \mu A \times 0.035)$$

+ $(200 \ \mu A \times 0.016)$ + $(2.0 \ \mu A)$

 $= 11.54 \ \mu A + 3.2 \ \mu A + 2 \ \mu A$

= 17.2 µA.

With burst-mode programming, the system consumes an average current of only 17.2 μ A and easily surpasses the target of 38.0 μ A required for 3-year battery life. The additional power reserve can be used to compensate for other requirements such as faster sampling, sensor signal conditioning, or weak/leaky batteries. Also, the current budgeting does not take into account the power required to support the activity if a trigger event occurs—i.e., glass breakage or fire detection. It is thought that these events would be very rare and clearly the exception to normal operation.

Further reduction in power consumption

It has been demonstrated that managing the system active duty cycle is of utmost importance for reducing power consumption in intelligent sensing applications. The primary goal should be to minimize active time and maximize time in standby and power-down modes. MCU code execution should be fast and efficient. MCU activity should be event-driven and use interrupts that identify the code to be executed as fast as possible; i.e., avoid cyclewasting subroutine calls, polling, and bit-test skip chains. The watch crystal and DCO combination is ideal for batterypowered applications, providing both an ultra-low-power standby mode and a fast processor clock. The fact that the DCO can start and is stable in less than 6 µs provides very large power savings by reducing start-up time. The start-up time for a typical crystal or resonator is in the 10-ms range-time that would be wasted and consume significant power. Using the DCO can reduce standby-to-active wake-up time by over $1000 \times$.

The ADC must also be powered down as long as possible. If more limited resolution data can be used, consider short cycling. That is, inspect only the first 8 bits of ADC conversion code (which represent the 5 MSB of the conversion) in the first of two SPI transfers required for a complete conversion. Determine if the first 5 bits are interesting; if not, terminate the second SPI transfer to power down the ADC.

In all cases, if a voltage regulator or step-up converter is used, reduce system V_{CC} as much as possible. All components will use less power at a lower $V_{CC}.$

Description of the demonstration program

The code is short, interrupt-driven, and programmed in assembler. This combination ensures that the MCU executes code as fast and effectively as possible with no power-wasting extra cycles.

The demonstration firmware is coded with a Mainloop and single active WDT interrupt service routine (ISR). Three MSP430F123 USART pins on port 3 are used to interface with the ADS7822 ADC, and port 1 pin P1.0 is used as a status indicator. All MSP430 port pins default to the input direction. In a final application, unused pins should be configured to the output direction to avoid power-consuming floating inputs.

The code demonstration firmware first initializes the peripherals. Next, inside the Mainloop, setting the appropriate bits in the CPU status register (SR) forces the processor to enter LPM3:

Mainloop bis.w #LPM3,SR ; Enter LPM3

The CPU, DCO, and code execution halt at this point, but the pre-configured 2-ms WDT ISR is active with the timer clocked by the 32-kHz ACLK. It is at this point that the code spends the vast majority of time with the MCU and ADC in a battery-conserving standby mode; only the ACLK and WDT are active.

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As with all MSP430 ISRs, the program counter (PC) and SR are automatically saved on the stack, and the CPU is returned to active. This ensures that the ISR can always be processed, even from a low-power mode. The ISR places the WDT vector on the PC, and code execution begins. Inside the WDT ISR, P3.0 resets \overline{CS} , enabling the ADS7822. The ADC is sampled and then \overline{CS} is set, returning the ADC to power-down. For demonstration purposes, if the 12-bit ADC code is greater than 2,048, the Mainloop is made active after the WDT ISR by clearing the LPM3 bit on the top of the stack (TOS) that holds the previous SR. Manipulating the PC on the TOS is an excellent technique for using events to manage system activity and low-power modes.

bic.w #LPM3,0(SP) ; Exit LPM3 on reti

An active Mainloop will toggle port pin P1.0, indicating a trigger to action in a user application. If the ADC code is less than 2,048, the system returns to LPM3. The WDT ISR operates continuously at the programmed 2-ms interval. In an actual end application, a more complex decision/action than a simple comparison/pin toggling could be made when the sensor data is interesting.

References

For more information related to this article, you can download an Acrobat Reader file at www-s.ti.com/sc/techlit/ *litnumber* and replace *"litnumber"* with the **TI Lit. #** for the materials listed below.

Document Title TI Lit.

- 1. MSP430x1xx Family User's Guideslau049
- 3. "12-Bit High-Speed 2.7 V microPower Sampling Analog-to-Digital Converter,"
- ADS7822 Data Sheetsbas062 4. "TPS60310, TPS60311, TPS60312, TPS60313 Single-Cell to 3-V/3.3-V, 20-mA

Related Web sites

www.ti.com/sc/docs/products/analog/device.html Replace *device* with ads7822, msp430f123 or tps60311

#include "msp430x12x.h"								
	ORG	0E000h	;	Program Start				
, RESET	mov.w	#0300h,SP	;	Initialize `x12x stack				
SetupWDT	mov.w	#WDT_ADLY_1_9,&WDTCTL	;	WDT 1.9ms, ACLK, interval timer				
	bis.b	#WDTIE,&IE1	;	Enable WDT interrupt				
SetupDCO	mov.b	#0C0h,&DCOCTL	;	; DCO~1MHz				
SetupP1	bis.b	#01h,&P1DIR	;	; P1.0 output direction				
SetupP3	bis.b	#OEh,&P3SEL	;	P3.1-3 SPI option select				
	bis.b	#01h,&P3DIR	;	P3.0 output direction				
SetupSPI	bis.b	#USPIE0,&ME2	;	Enable USARTO SPI				
	bis.b	#CKPH+SSEL1+SSEL0+STC,&UTCTL0	;	SMCLK, 3-pin mode				
	mov.b	#CHAR+SYNC+MM, &UCTL0	;	8-bit SPI Master **clear SWRST*				
	mov.b	#02h,&UBR00	;	SMCLK/2 for baud rate				
	clr.b	&UBR10	;					
	clr.b	&UMCTL0	;	Clear modulation				
	eint		;	Enable interrupts				
			;					
Mainloop	bis.w	#LPM3,SR	;	Enter LPM3				
NC	bis.b	#001h,&P1OUT	;	P1.0 = 1 - LED ON				
OFF	bic.b	#001h,&P1OUT	;	P1.0 = 0 - LED OFF				
	jmp	Mainloop	;					

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MSP430F123/ADS7822 demonstration program (Continued)

Meas 7822	bic.b	#CS,&P3OUT	;	/CS reset, enable ADC		
	mov.b	#00h,&TXBUF0		Dummy write to start SPI		
	mov.b	#00h,&TXBUF0		Dummy write to start SPI		
	bic.b	#URXIFG0,&IFG2		Clear errant RXBUF flag		
RX_MSB	bit.b	#URXIFG0,&IFG2		RXBUF ready?		
	jnc	RX MSB		1 = empty		
	mov.b	&RXBUF0,R15		R15 = 00 MSB		
	swpb	R15		R15 = MSB 00		
RX LSB	bit.b	#URXIFG0,&IFG2		RXBUF ready?		
	jnc	RX LSB	;	1 = empty		
	bis.b	#CS,&P3OUT	;	/CS set, disable ADC		
	mov.b	&RXBUF0,R14	;	R14 = 00 LSB		
	add.w	R14,R15	;	R15 = MSB LSB		
	rrc.w	R15	;	·		
	and.w	#0FFFh,R15	;	Keep only databits		
	cmp.w	#2048,R15	;			
	jlo	No_action	;	jump if 2048 < R15		
	bic.w	#LPM3,0(SP)	;	Exit LPM3 on reti		
No_action	reti		;			
			;			
;;	Interrupt Vectors Used MSP430F12x					
	ORG	OFFFEh	;	MSP430 RESET Vector		
	DW	RESET	;			
	ORG	0FFF4h	;	WDT Vector		
	DW	WDT_ISR	;			
	END					

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